

In the Claims

The claims have been amended as follows:

1 ~~Sub~~ 1. (Amended) A method to enhance integrated circuit device heat
2 ~~DI~~ dissipation comprising the steps of:
3 providing an integrated circuit device having a surface;
4 providing a flexible corrugated tape strip of a thermal conductive
5 material having a flat flexible tape strip of a thermal conductive
6 material bonded to one side thereto forming a single-faced flexible
7 corrugated tape strip article; and
8 adhering the tape strip article to the surface of the integrated circuit
9 device.

1 2. (Canceled)

1 ~~Sub~~ 3. (Amended) The method of claim 1 wherein the tape strip is metal
2 ~~DI~~ and is copper or aluminum.

Sub
D1
ent

4. (Amended) The method of claim 3 wherein the thickness of the tape strip used to make the corrugated tape strip and the flat flexible tape strip are both about 0.5 mil to 10 mil.

5. (Withdrawn)

Sub
D1
ent

6. (Original) The method of claim 4 wherein the corrugations in the strip are in the shape of a repeating series of convex and concave portions comprising sidewall portions, top portions and bottom portions.

Sub
D1
ent

- 7.-10. (Withdrawn)

11. (Canceled)

Sub
D1
ent

12. (Amended) The method of claim 1 wherein the flat flexible tape strip article has an adhesive thereon on the side to be adhered to the integrated circuit device.

13. (Amended) The method of claim 1 wherein the single-faced flexible corrugated tape strip article has a flat flexible tape strip of thermal

3 | conductive material bonded to the other side of the flexible corrugated tape
4 | strip forming a double-faced flexible corrugated tape strip article.

1 | 14.-15. (Withdrawn)

1 *Sub P1* 16. (Amended) A method to enhance integrated circuit device heat
2 | dissipation comprising the steps of:

3 | providing an integrated circuit device having a surface;

4 | providing a tape strip of flexible flat thermal conductive material;

5 | forming corrugations in the tape strip of the flexible thermal conductive
6 | material;

7 | bonding a thermal conductive material flat tape strip to one side of the

8 | flexible corrugated tape strip forming a single-faced flexible

9 | corrugated tape strip article; and

10 | adhering the single-faced flexible corrugated tape strip article to the
11 | surface of the integrated circuit device.

1 | 17.-18. (Withdrawn)

1 | 19. (Canceled)

20. (Amended) The method of claim 16 wherein an adhesive is applied to the side of the single-faced corrugated tape strip article to be adhered to the integrated circuit device.

21. (Amended) The method of claim 16 wherein a second flexible tape strip thermal conductive material is bonded to the other side of the corrugated tape strip flexible thermal conductive material forming a double-faced corrugated tape strip article.

22.-23. (Withdrawn)

24. (Amended) An article of manufacture for dissipating heat for integrated circuit devices comprising a corrugated flexible tape strip of thermal conductive material having a flat flexible tape strip of a thermal conductive material bonded to one side thereto forming a single-faced flexible corrugated tape strip article.

25.-26. (Canceled)

27. (Amended) The article of claim 24 wherein the flat tape strip of thermal conductive material has an adhesive on the side to be adhered to an integrated circuit device.

28. (Amended) The article of claim 24 wherein a second flat flexible tape strip of thermal conductive material is bonded to the other side of the corrugated flexible tape strip material to form a double-faced flexible corrugated tape strip article.

29.-34. (Canceled)
